



NOTE: For the period of 10/1/2019 through 1/10/2020, due to a data irregularity in the customer impact lists, some indirect sales customers may not have received product change, product discontinuance, or product bulletin notices as expected through email. Although these notifications were published on our public portal (<https://www.onsemi.com/PowerSolutions/pcnPub.do>), ON Semiconductor is taking the action to redistribute affected notices, with revised implementation dates conforming to external standards and ON Semiconductor's customer notification policies. This issue has been resolved. Questions related to this issue can be directed to PCN.Support@onsemi.com

Title of Change:	Update to FPCN23099X - QFN 48/64L assembly site transferred from SPEL to AESH (Assembly only).
Proposed First Ship date:	25 Jun 2020 or earlier if approved by customer
Contact Information:	Contact your local ON Semiconductor Sales Office or Naruedol.Srisamran@onsemi.com
PCN Samples Contact:	Contact your local ON Semiconductor Sales Office or < PCN.samples@onsemi.com >. Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.
Additional Reliability Data:	Contact your local ON Semiconductor Sales Office or Frank.Tuan@onsemi.com
Type of Notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change. ON Semiconductor will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact PCN.Support@onsemi.com
Marking of Parts/ Traceability of Change:	Trace code marking will change from SL(WLYYWW)G to AS(WLYYWW)G, where WL is Wafer Lot Number, WW is Work Week Number, YY is Year of Production.
Change Category:	Assembly Change
Change Sub-Category(s):	Manufacturing Site Transfer

Sites Affected:

ON Semiconductor Sites	External Foundry/Subcon Sites
None	AESH, China
	SPEL Semiconductor Limited

Description and Purpose:

Transfer Assembly only for QFN48L and 64L from SPEL to AESH including change in Leadframe design, Die attach epoxy material and mold material.

QFN64L

	Before Change Description	After Change Description
LeadFrame	C194 with flag size 6.18 x 6.18 mm	C7025 with flag size 6.0 x 6.0 mm
Die Attach	CRM1076NS	EN-4900GC
Mold Compound	G770 HCD	G631H
Assembly Site	SPEL	ASE Shanghai

QFN48L

	Before Change Description	After Change Description
LeadFrame	C194 with flag size 4.0 x 4.0 mm	C194 with flag size 4.0 x 4.0 mm
Die Attach	CRM1076NS	EN-4900GC
Mold Compound	G770 HCD	G631H
Assembly Site	SPEL	ASE Shanghai



Reliability Data Summary:

QV DEVICE NAME: NB3W1200LMNTXG

RMS : O58293

PACKAGE : QFN64

Test	Specification	Condition	Interval	Result
HTOL	JESD22-A108	Ta= 125°C, 100 % max rated Vcc	504 hrs	0/240
HTSL	JESD22-A103	Ta= 150°C	1008 hrs	0/240
TC	JESD22-A104	Ta= -65°C to + 150°C	500 cyc	0/240
HAST	JESD22-A110	130°C, 85% RH, 18.8psig, bias	96 hrs	0/240
UHAST	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs	0/240
PC	J-STD-020 JESD-A113	MSL 3 @ 260°C		0/240
SD	JSTD002	Ta = 245C, 10 sec		0/45

Electrical Characteristics Summary:

Electrical characteristics are not impacted.

List of Affected Parts:

*Note: Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the **PCN Customized Portal**.*

Part Number	Qualification Vehicle
NB3W800LMNTWG	NB3W1200LMNTXG
NB3W800LMNTXG	NB3W1200LMNTXG
NB3N1200KMNG	NB3W1200LMNTXG
NB3N1200KMNTXG	NB3W1200LMNTXG
NB3W1200LMNG	NB3W1200LMNTXG
NB3W1200LMNTXG	NB3W1200LMNTXG
NB3W800LMNG	NB3W1200LMNTXG



Appendix A: Changed Products

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Product	Customer Part Number	Qualification Vehicle	New Part Number	Replacement Supplier
NB3W1200LMNG		NB3W1200LMNTXG		
NB3N1200KMNG		NB3W1200LMNTXG		